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Mechanical standardization of semiconductor devices –

Part 6-16: Glossary of semiconductor tests and burn-in sockets for BGA, LGA, FBGA and FLGA



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MECHANICAL STANDARDIZATION OF SEMICONDUCTOR DEVICES –

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International Standard IEC 60191-6-16 has been prepared by subcommittee 47D: Mechanical standardization of semiconductor devices, of IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47D/679/FDIS	47D/683/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directive, Part 2.

A list of all the parts of the IEC 60191 series, under the general title *Mechanical standardization of semiconductor devices*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

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1 Scope

This part of IEC 60191 gives a glossary of semiconductor sockets for BGA, LGA, FBGA and FLGA. This standard intends to establish definitions and unification of terminology relating to tests and burn-in sockets for BGA, LGA, FBGA and FLGA.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60191-1:1966, *Mechanical standardization of semiconductor devices – Part 1: Preparation of outline drawings of semiconductor devices*

IEC 60191-2:1966, *Mechanical standardization of semiconductor devices – Part 2: Dimensions*

IEC 60191-3:1999, *Mechanical standardization of semiconductor devices – Part 3: General rules for the preparation of outline drawings of integrated circuits*

IEC 60191-4:1999, *Mechanical standardization of semiconductor devices – Part 4: Coding system and classification into forms of package outlines for semiconductor devices*